

Small Signal Product

Taiwan Semiconductor

400mW Trigger Diode (DIAC)

FEATURES

- Surface Mount Device SOD-123 packaged
- V_{BO}=32V DB3
- Max. P_D=400mW

MECHANICAL DATA

- Case: Plastic gull wing SOD-123 package
- High temperature soldering guaranteed: 260°C/10s
- Weight: 10.55mg (approximately)
- Moisture sensitivity level (MSL): 1
- Pb free and RoHS compliant

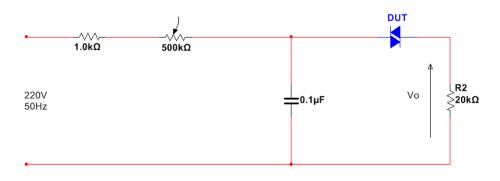
APPLICATION

- These diacs are intended for use in thyrisitors phase control, circuits for lamp dimming, universal motor speed control, and heat control

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)						
PARAMETER		SYMBOL	VALUE	UNIT		
Repetitive Peak on-state Current	tp=20µs, f=100Hz	I _{TRM}	2	А		
Power Dissipation		P _D	400	mW		
Junction Temperature		TJ	- 40 to +125	°C		
Storage Temperature Range		T _{STG}	- 40 to +125	°C		

PARAMETER		SYMBOL	MIN TYP		MAX	TEST CONDITION	UNIT
Poverse Preakdown Valtage	SODDB3	М	28	32	36	C=22nF	V
Reverse Breakdown Voltage	SODDB3T	V _{BO}	30	32	34	0=2211F	v
Breakdown Voltage Symmetry	SODDB3	[+V _{BO1} -	[+V _{B01} - ±3		C=22nF	V	
	SODDB3T	-V _{BO2}]			±2	C=22NF	v
Dynamic Breakdown Voltage	SODDB3		5				V
	SODDB3T	∆V±	9			\triangle I=[I _{BO} to I _F =10mA]	V
Repetitive Peak on-state Current		I _{TRM}	2			t _P =20μs, f=100Hz	Α
Output Voltage		Vo	5			Note	V
Leakage Current		I _R	-		10	$V_B = 0.5 V_{BO}$	μA
Rest Time		t _r		1.5			μs
Breakdown current	SODDB3				100	- C=22nF	
	SODDB3T	I _{BO}	-		15		μA

Note: Test circuit for output voltage









SOD-123

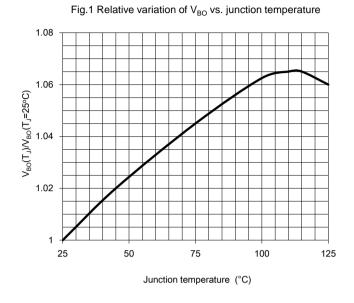


SODDB3/SODDB3T Taiwan Semiconductor

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RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)



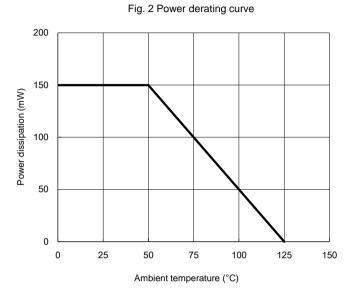
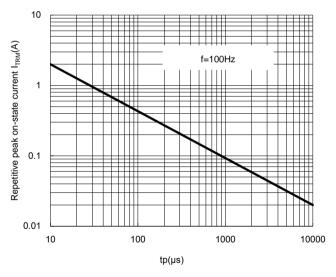


Fig. 3 Peak pulse current vs. pulse duration





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ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
SODDBxx (Note 1, 2)	RH	G	SOD-123	3K / 7" Reel	

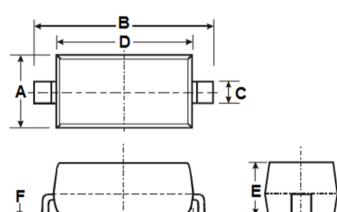
Note 1: "x" is Device Code from "3" - "3T".

Note 2: Whole series with green compound

EXAMPLE					
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
SODDB3 RHG	SODDB3	RH	G	Green compound	

PACKAGE OUTLINE DIMENSIONS

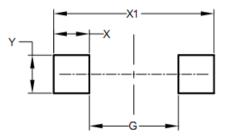




G

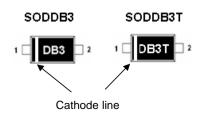
DIM.	Unit	(mm)	Unit (inch)		
DINI.	Min	Min Max		Max	
А	1.40	1.80	0.055	0.071	
В	3.55	3.85	0.140	0.152	
С	0.45	0.70	0.018	0.028	
D	2.55	2.85	0.100	0.112	
Е	0.95	1.35	0.037	0.053	
F	0.05	0.15	0.002	0.006	
G	0.50 REF		0.02	REF	
Н	-	0.10	-	0.004	

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)		
DINI.	Min	Min		
G	2.25	0.089		
Х	0.90	0.035		
X1	4.05	0.159		
Y	0.95	0.037		

MARKING



Note: Apply positive voltage in cathode line and apply negative in another electrode, it will show better I/V curve. It help user differentiate the direction of purpose.

0.50 REF 0.02 REF - 0.10 - 0.004



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